
MPC8610 Chip Errata

This document details all known silicon errata for the MPC8610 device. The following table provides a revision history for this document.

Table 1. Document Revision History

Revision	Date	Significant Changes
0	01/2010	Initial public release

Revision Level to Part Marking Cross-Reference

The following table provides a cross-reference to match the revision code in the processor version register to the revision level marked on the device.

Table 2. Revision Level to Part Marking Cross-Reference

Part	Revi-sion	e600 Core Revision	Device Marking	Processor Version Register Value	System Version Register Value
MPC8610	1.1	2.2	B	0x8004_0202	0x80A0_0011

Table 3 summarizes all known errata for blocks on the MPC8610 and lists the corresponding silicon revision level to which it applies. A 'Yes' entry indicates the erratum applies to a particular revision level, while a 'No' entry means it does not apply.

Note

Table 3. Summary of Silicon Errata and Applicable Revision

Errata	Name	Projected Solution	Silicon Rev.
			1.1
DDR			
DDR 1	Automatic data initialization and DLL resets to DRAM are not performed correctly if CS2 and CS3 are interleaved	No plans to fix	Yes

Errata	Name	Projected Solution	Silicon Rev.
			1.1
DDR 2	Memory contents may not be retained during HRESET sequence	No plans to fix	Yes
DMA			
DMA 1	DMA_DACK bus timing violation when operating in external DMA master mode	No plans to fix	Yes
DUART			
DUART 1	BREAK detection triggered multiple times for a single break assertion	No plans to fix	Yes
e600			
e600 1	Unexpected instruction fetch may occur when mtmsr/isync transitions MSR[IR] from 1 to 0 and isync instruction resides in unmapped page	No plans to fix	Yes
e600 2	<i>core_mcp</i> or <i>core_reset</i> signal assertion during transition to Nap may hang processor	No plans to fix	Yes
e600 3	Unpaired stwcx. may hang processor	No plans to fix	Yes
GEN			
GEN 1	CPU-only reset may result in a failure in the platform logic	No plans to fix	Yes
I2C			
I2C 1	Enabling I ² C could cause I ² C bus freeze when other I ² C devices communicate	No plans to fix	Yes
JTAG			
JTAG 1	Debug visibility unattainable without COP warm-up clock bit set during HRESET assertion	No plans to fix	Yes
JTAG 2	Store-type operations during COP softstop debug mode may hang processor; Machine check error limitations	No plans to fix	Yes
JTAG 3	Boundary scan test on SerDes transmitter pins needs special requirement incompliant to IEEE 1149.1 specification	No plans to fix	Yes
eLBC			
eLBC1	Multi-bank DRAM and SDRAM will not work without any external logic	No plans to fix	Yes
eLBC 2	LTEATR and LTEAR may show incorrect values under certain scenarios	No plans to fix	Yes
eLBC 3	UPM does not have indication of completion of a Run Pattern special operation	No plans to fix	Yes
MCM			
MCM 1	Unmapped tlbie EA causes local access window error	No plans to fix	Yes
PEX			
PEX 2	Completion Timeout error disable corrupts CRS threshold error data	No plans to fix	Yes
PEX 3	No mechanism for recovery from hang after access to down link	No plans to fix	Yes

Errata	Name	Projected Solution	Silicon Rev.
			1.1
PEX 4	Reads to PCI Express CCSR or local config space temporarily return all Fs	No plans to fix	Yes
PCI			
PCI 1	Assertion of <u>STOP</u> by a target device on the last beat of a PCI memory write transaction can cause a hang	No plans to fix	Yes
SPI			
SPI 1	Selection of GPIO functionality on SPISEL signal causes MME in SPI	No plans to fix	Yes
PMON			
PMON 1	Some local bus events are not counted correctly in the performance monitor	No plans to fix	Yes

DDR 1: Automatic data initialization and DLL resets to DRAM are not performed correctly if CS2 and CS3 are interleaved

Description:	CS2 and CS3 can be interleaved together by setting DDR_SDRAM_CFG[BA_INTLV_CTL] to 7'bx1xx0x0. In this mode, the DDR controller may operate incorrectly for 2 different features. First, the DDR controller will not initialize DRAM data properly if DDR_SDRAM_CFG_2[D_INIT] is set. If D_INIT is set with CS2 and CS3 interleaved together, then the memory spaced defined by CS2 and CS3 will not be initialized. Second, the DDR controller may not issue DLL reset commands to CS2 and CS3 when exiting self refresh. Note that this feature is typically enabled when DDR_SDRAM_CFG_2[DLL_RST_DIS] is cleared. If CS0 and CS1 are both disabled via CSn_CONFIG[CS_n_EN] (and CS2 and CS3 are interleaved together), then only CS3 will receive the DLL reset command when self refresh is exited. Note that neither of these issues will be present if all chip selects are enabled and CS0-CS3 are interleaved together.
Impact:	There are 2 results that can be observed from this erratum. If the first scenario listed above is present, then the memory space defined by CS2 and CS3 will not be initialized properly when DDR_SDRAM_CFG_2[D_INIT] is set. If the second scenario listed above is present, then the DLL reset command will not be issued as expected to CS2. It is not expected that this will cause any issues with DDR2 memories. DDR2 JEDEC specifications state that the DRAM's DLL is automatically disabled when entering self refresh, and the DLL is automatically reenabled when exiting self refresh. Although it would be possible for some vendors to vary, the DLL reset should not be required by the DRAMs when exiting self refresh. The DLL reset feature was originally added to support DDR1 memories. It appears that DDR1 memories will typically only require the DLL reset when the frequency is changed, but this scenario should still be avoided if possible to prevent any potential issues.
Workaround:	There are several workarounds for this erratum. The preferred workaround will be to disable interleaving between CS2 and CS3. CS0 and CS1 can still be interleaved together. In addition, CS0 and CS3 could still be interleaved together without any issues. If it is still preferred to interleave CS2 and CS3 together, then one of two workarounds can be used for initializing memory. First, software could be used to initialize memory (i.e., via the DMA) instead of using DDR_SDRAM_CFG_2[D_INIT]. In addition, the memory controller could be enabled without CS2 and CS3 interleaved while DDR_SDRAM_CFG_2[D_INIT] is set. After D_INIT is cleared by the hardware, CS2 and CS3 could then be programmed to be interleaved together (via DDR_SDRAM_CFG[BA_INTLV_CTL]). The memory space defined by the CS2_BNDS register would then need to be updated to include the entire memory space for CS2 and CS3. During this entire sequence, software would need to guarantee that no other transactions are issued to memory.

Other than disabling interleaving between CS2 and CS3, the only other way to workaround the DLL reset issue is to ensure that either CS0 or CS1 is also enabled (via CSn_CONFIG[CS_n_EN]).

Fix plan: No plans to fix

DDR 2: Memory contents may not be retained during HRESET sequence

Description: It may be desirable for customers to have the DDR controller enter self refresh mode and HRESET the part shortly after, while retaining contents of memory. However, it is possible that CKE will not be driven active low during HRESET, bringing the DRAM out of self refresh.

There are pin-sampled signals that may erroneously place the DDR into a test mode if they are not set to a valid state when HRESET is asserted. The DDR controller should drive the MCKE[0:3] pins active low throughout and after HRESET. However, when this test mode is entered, the DDR drivers will be inactive, and the MCKE[0:3] pins will be released to high impedance. This test mode will be entered if a value of 0xf is presented on LA[28:31] during HRESET, or if a value of 0x0 is presented on MSRCID[2] during HRESET. The MCKE[0:3] pins will remain released to high impedance until LA[28:31] and MSRCID[2] are set correctly for pin sampling.

There are POR configuration signals sampled during HRESET that do not quickly achieve correct values using their internal pull-ups that may erroneously place the chip into a test mode temporarily. The DDR controller should drive the MCKE[0:3] pins active low throughout and after HRESET. However, when the DDR controller enters a test mode, the DDR MCKE driver will be released to high impedance or driven high, preventing the MCKE[0:3] pins from being driven low immediately after HRESET.

This test mode will be entered if a value of 0xf is presented on LA[28:31] during HRESET, a value of 0x0 is presented on TSEC2_RXD[4] and TSEC2_TX_ER, or if a value of 0x0 is presented on D1_MSRCID[2] during HRESET. The MCKE[0:3] pins will remain released to high impedance or driven high until LA[28:31], TSEC2_RXD[4], TSEC2_TX_ER and D1_MSRCID[2] are set correctly for pin sampling.

Impact: The DRAMs may erroneously exit self refresh mode if MCKE is released to high impedance and transitions above the minimum AC switching voltage level.

Workaround: Depending upon the board application, it may be possible to use active components during HRESET to ensure that MCKE[0:3] will remain low throughout HRESET.

Fix plan: No plans to fix

DMA 1: DMA_DACK bus timing violation when operating in external DMA master mode

Description: The specification requires the external DMA master signal DMA_DACK to be held for at least three system clocks. The DMA may violate this requirement, depending on the internal latency of a transaction. The DMA asserts DMA_DACK based on an internal 'write done' signal, which varies depending on the write target and whether it is the last write of a transaction.

For MPX/platform to SYSCLK ratios of 9:1 or larger, in some cases, the 'write done' signal asserts too quickly, causing the DMA_DACK to be held for too short a time. MPX/platform to SYSYCLK ratios smaller than 9:1 are unaffected.

Impact: DMA_DACK does not meet minimum hold specification of 3 SYSCLK cycles.

Workaround: Option 1: Run MPX:SYSCLK ratio of 8:1 or smaller.

Option 2: Program the descriptors so each link descriptor can be handled in one transaction. The last write of a descriptor uses a write-with-response transaction, and therefore is delayed enough to meet the DMA_DACK spec regardless of MPX:SYSCLK ratio.

Option 3: The following scenarios are the possible MPX:SYSCLK ratios greater than 8:1 available on MPC8610 and their respective workarounds.

1. SYSCLK = 33 MHz, MPX = 333 (10:1), MPX:OCeaN = 1:1

Workaround: Use DMA byte count > 64 bytes, or do not rely on DMA_DACK, or implement Option 2 above.

2. SYSCLK = 33 MHz, MPX = 333 (10:1), MPX:OCeaN = 2:1

This configuration is not affected by this erratum. The DMA controller will function as expected.

3. SYSCLK = 33 MHz, MPX = 400 (12:1), MPX:OCeaN = 1:1

Workaround: Do not rely on DMA_DACK or implement Option 2 above.

4. SYSCLK = 33 MHz, MPX = 400 (12:1), MPX:OCeaN = 2:1

This configuration is not affected by this erratum. The DMA controller will function as expected.

5. SYSCLK = 33 MHz, MPX = 533 (16:1), MPX:OCeaN = 1:1

This configuration is not supported on MPC8610. The MPX to OCeaN ratio must be set to 2:1 through the cfg_net2_div configuration signal for MPX frequencies above 400 MHz.

6. SYSCLK = 33 MHz, MPX = 533 (16:1), MPX:OCeaN = 2:1

This configuration is not affected by this erratum. The DMA controller will function as expected.

Fix plan: No plans to fix

DUART 1: BREAK detection triggered multiple times for a single break assertion

Description: A UART break signal is defined as a logic zero being present on the UART data pin for a time longer than (START bit + Data bits + Parity bit + Stop bits). The break signal persists until the data signal rises to a logic one.

A received break is detected by reading the ULSR and checking for BI=1. This read to ULSR will clear the BI bit. Once the break is detected, the normal handling of the break condition is to read the URBR to clear the ULSR[DR] bit. The expected behavior is that the ULSR[BI] and ULSR[DR] bits will not get set again for the duration of the break signal assertion. However, the ULSR[BI] and ULSR[DR] bits will continue to get set each character period after they are cleared. This will continue for the entire duration of the break signal.

At the end of the break signal, a random character may be falsely detected and received in the URBR, with the ULSR[DR] being set.

Impact: The ULSR[BI] and ULSR[DR] bits will get set multiple times, approximately once every character period, for a single break signal. A random character may be mistakenly received at the end of the break.

Workaround: The break is first detected when ULSR is read and ULSR[BI]=1. To prevent the problem from occurring, perform the following sequence when a break is detected:

1. Read URBR, which will return a value of zero, and will clear the ULSR[DR] bit
2. Delay at least 1 character period
3. Read URBR again, which will return a value of zero, and will clear the ULSR[DR] bit

ULSR[BI] will remain asserted for the duration of the break. The UART block will not trigger any additional interrupts for the duration of the break.

This work around requires that the break signal be at least 2 character-lengths in duration.

This work around applies to both polling and interrupt-driven implementations.

Fix plan: No plans to fix

e600 1: Unexpected instruction fetch may occur when mtmsr/isync transitions MSR[IR] from 1→0 and isync instruction resides in unmapped page

Description: If the **mtmsr** instruction is used to disable instruction translation, and the subsequent **isync** instruction resides on a different page than the **mtmsr** instruction, and the **isync** instruction's page causes a page fault exception, the e600 core will hang before taking the page fault exception. Once in the hang state, the e600 core will not recover and hard reset must be asserted.

An alternate failing scenario can exist if the **mtmsr** and **isync** reside on the same page but in different quadwords. If the mapping for that page exists in the iTLB, but not the page table, and a tlbie snoop occurs between the **mtmsr** and **isync** that invalidates the iTLB entry, then the processor will hang before taking the page fault exception.

If the **isync** instruction address is guaranteed to have a valid page table mapping resident in the memory hierarchy, then neither scenario can occur.

Impact: Any systems that disable instruction translation using **mtmsr**, and for which the required **isync** may reside in a different page whose page table entry is not available in the memory hierarchy may hang.

Any systems mapping the **mtmsr/isync** code with the IBATs will not fail due to this issue. Any systems not demand-paging their supervisor-level code will not fail due to this issue.

Workaround: Any of the following work-arounds will avoid the e600 core from hanging:

- **mtmsr/isync** instruction pairs should reside within the same quadword.
- disable instruction translation by initializing SRR0/SRR1 and executing **rfi**.
- map code which disables instruction address translation with the IBATs.

Fix plan: No plans to fix

e600 2: core_mcp or core_sreset signal assertion during transition to Nap may hang processor

Description: On the MPC8610, all internal interrupt signals to the processor core, excluding core_smci, are prioritized and delivered by the programmable interrupt controller (PIC). The core_smci signal is delivered to the processor via the global utilities block from the external SMI signal. Please refer to the PIC chapter in the device reference manual for more information on these internal signals.

If the machine check signal (core_mcp) or soft reset signal (core_sreset) are asserted in a window after MSR[POW] has been set but before the processor has asserted the quiesce request signal (qreq), then the processor may encounter a hang condition.

The nap entry sequence in the e600 Core User's Manual is as follows:

```
loop: sync
mtmsr POW
isync
b loop
```

Legacy software entering nap using this entry sequence are not affected:

```
sync
mtmsr POW
isync
loop: b loop
```

The fail occurs when an outstanding out-of-order instruction fetch occurring before the **mtmsr**, but not having received data and the results of which are no longer needed for execution, extends the window between the setting of POW and the assertion of qreq by the processor. If the Branch Target Instruction cache (BTIC) is enabled, and the Nap entry code is in the BTIC due to a previous execution of this code, then the instructions from the sequence can be loaded into the completion buffer the cycle after execution has halted. If the core_mcp or core_sreset signals are asserted at this point, they will void the entry into Nap as architected. However, both events require the completion buffer to be empty for their exceptions to be processed. Completion is halted, though, so no exceptions are processed and the hang occurs. The core_smci and int signal assertions do not require the completion buffer to be empty and therefore do not cause a hang.

Impact: Systems where core_mcp or core_sreset can be asserted during entry into Nap mode are at risk. On the MPC8610 processor, critical interrupts, including Message-Shared, Message, and External interrupt sources, are mapped to the e600 core_mcp input. Therefore, risk of failure is greater than for devices with external interrupt signals to the processor cores.

Workaround: Systems can implement any one of the following changes to work around this issue:

1. Use the legacy code entry sequence to enter Nap.
2. Disable the BTIC before entering Nap.

3. Invalidate the Nap entry code using an **icbi** instruction after taking the exception (a decrementer exception for example) that awakens the processor from Nap state.

Fix plan: No plans to fix

e600 3: Unpaired **stwcx.** may hang processor

Description:

In general, **Iwarx** and **stwcx.** instructions should be paired, with the same effective address used for both. The only exception is that an unpaired **stwcx.** instruction to any (scratch) effective address can be used to clear any reservation held by the processor.

When a **stwcx.** is unpaired, the e600 core may encounter an unexpected hang condition if each of the following is true:

1. Initial condition

```
RESERVE bit = 1 (due to previously executed Iwarx)
Reservation = address A
Instruction executed = stwcx. to address B, resident in
dL1 in Modified or Exclusive state
dL1 modified entry = address C
```

2. An external snoop to address A of a type shown in the following table occurs while the **stwcx.** is being processed by the Load/Store Unit.

Table 4. Snooped Store Types that Cancel a Reservation

Command	TT
Write-with-flush	0x02
Write-with-kill	0x06
Kill block	0x0C
Read-with-intent-to-modify	0x0E
Read claim	0x0F
Read-with-intent-to-modify-atomic (stwcx.)	0x1E

3. An external snoop to address C follows the snoop to address A while the **stwcx.** is being processed by the Load/Store Unit.

Normally, the snoop to address A would clear the RESERVE bit, and the snoop to address C would initiate a snoop push of the modified line from the dL1. The **stwcx.** may succeed or fail depending on when the snoop to A cleared the RESERVE bit, but the completion of the **stwcx.** should be reported regardless.

A one cycle window exists wherein the above sequence will cause the Load/Store Unit to not report the completion of the **stwcx.** to the Completion Unit. As a result, the processor will hang. The hang can only be cleared by asserting hard reset.

Impact:

The processor will hang if the Load/Store Unit does not report the completion of the **stwcx.** to the completion unit. Paired **Iwarx/stwcx.** instructions are not affected by this erratum. Most operating systems include an unpaired **stwcx.** at the end of exception handler code and context switch code to clear the RESERVE bit before returning to normal execution. Note that **stwcx.** is a user level instruction.

Non-SMP environments are less susceptible to this erratum due to the requirement of an external snoop to address A which holds the reservation from a previous **Iwarx** instruction. Most operating systems do not allow a snoop to be initiated by an external peripheral to an address that the core wants to reserve in a non-SMP environment. If the non-SMP environment's operating system does not allow such snoops, then the environment will not be affected by this erratum.

Workaround: Any individual one of the following steps can be taken to work around this issue:

- Place a **Iwarx** instruction to the same scratch address as the **stwcx.** immediately before the **stwcx.**, or
- Place a dcbf instruction to the same scratch address as the **stwcx.** immediately before the **stwcx.**, or
- Do not permit an external snoop to the address of the reservation address.

Interrupts must be disabled (MSR[EE] = 0) during the instruction sequences for the first two options. In most operating systems, interrupts are already disabled when an unpaired **stwcx.** is executed.

Fix plan: No plans to fix

GEN 1: CPU-only reset may result in a failure in the platform logic

Description:	The device provides the ability to assert the <i>core_sreset</i> signal to the processor. Once done, the possibility exists that the platform logic may fail.
Impact:	If <i>core_sreset</i> is asserted by setting PIR[P0], the possibility exists that the platform logic may fail.
Workaround:	The core must be reset via a full hard reset of the device.
Fix plan:	No plans to fix

I²C 1: Enabling I²C could cause I²C bus freeze when other I²C devices communicate

Description: When the I²C controller is enabled by software, if the signal SCL is high, the signal SDA is low, and the I²C address matches the data pattern on the SDA bus right after enabling, an ACK is issued on the bus. The ACK is issued because the I²C controller detects a START condition due to the nature of the SCL and SDA signals at the point of enablement. When this occurs, it may cause the I²C bus to freeze. However, it happens very rarely due to the need for two conditions to occur at the same time.

Impact: Enabling the I²C controller may cause the I²C bus to freeze while other I²C devices communicate on the bus.

Workaround: Use one of the following workarounds:

- Enable the I²C controller before starting any I²C communications on the bus. This is the preferred solution.
- If the I²C controller is configured as a slave, implement the following steps:
 - a. Software enables the device by setting I2CnCR[MEN] = 1 and starts a timer.
 - b. Delay for 4 I²C bus clocks.
 - c. Check Bus Busy bit (I2CnSR[MBB])

```
if MBB == 0
    jump to Step f; (Good condition. Go
    to Normal operation)
else
    Disable Device (I2CnCR[MEN] = 0)
```

- d. Reconfigure all I²C registers if necessary.
- e. Go back to Step a.
- f. Normal operation.

Fix plan: No plans to fix

JTAG 1: Debug visibility unattainable without COP warm-up clock bit set during `HRESET` assertion

Description: There is no debug visibility unless the warm-up clock bit, only accessible through the COP, is set during `HRESET` assertion.

Impact: An `HRESET` assertion on the board is required to gain debug visibility because the warm-up clock bit must be set during `HRESET` assertion. Debug of the device is not obtainable until the warm-up bit is set during `HRESET` assertion. All systems in development and in production will be affected including the following systems:

- Systems with the MPC8610 on a daughter card
- Systems in the field
- Systems in test before final production
- Systems in hardware and software debug labs

Workaround: Set the warm-up clock bit via the COP tool during `HRESET` assertion. This temporary solution will allow for debug visibility on lab and testing systems that can afford to be reset while debugging. However, for systems in the field this may not be an option because a reset will cause all error data to be lost.

For systems where the MPC8610 is on a daughter card, the above workaround will not solve the issue. A reset of the daughter card will set the warm-up clock bit, but the card itself will not be reliable for several reasons (i.e. it will not be synchronized with the motherboard and may not be able to be reset without a reset from the motherboard) There is not workaround for this type of system.

Fix plan: No plans to fix

JTAG 2: Store-type operations during COP softstop debug mode may hang processor; Machine check error limitations

Description: During softstop debug mode, the processor may incorrectly disable internal clocks before a store type operation has accessed the Platform/MPX bus. Softstop debug mode is accessible via the common on-chip processor (COP) and is used by emulator tools for debugging. The store type operations affected are:

CI store	eieio	tlbie	dcbf w/ data	dcbi	ecowx
WT store	tlbsync	dcbf	castout	icbi	

The store type operation would be retained in the bus store queue while the clocks were frozen. The retained store may cause the processor to violate the bus protocol either before entering or after resuming from softstop. The resulting protocol violation may hang the system, and require a hard reset to recover.

Possible protocol violations include but are not limited to:

1. A multi-cycle assertion of \overline{TS} as softstop is entered.
2. A \overline{TS} assertion after resuming from softstop that may not meet proper setup time.
3. A \overline{TS} assertion after resuming from softstop that is not preceded by a qualified \overline{BG} assertion.
4. A missed \overline{AACK} assertion.

Softstop debug mode via the COP is affected. Using the IABR/DABR and taking a trace or performance monitor interrupt during functional mode works as expected. The QREQ/QACK nap/sleep protocol also works as expected.

The COP softstop operations affected are those triggered by:

1. A direct COP softstop request.
2. An IABR or DABR match event.
3. An MSR[SE] or MSE[BE] event.
4. A performance monitor event.

The issue also affects functional operation mode. Normally, when a machine check exception occurs, any store type operations in the pipeline of the processor are required to complete to memory before the machine check exception is taken. Due to the erratum, the machine check exception may be taken while a solitary store type operation is present in the bus store queue. The only known impact of this behavior occurs if the solitary store type operation encounters a parity error or TEA error on the Platform/MPX bus, then the processor would checkstop due to taking a machine check exception while in the machine check exception handler.

Impact: Emulators that utilize the COP softstop feature may not work as intended since the processor's violation of the system bus protocol may cause unexpected behavior on the part of the system controller.

Extra delay is added between entry into softstop and the disabling of clocks on the MPC8610. Due to this characteristic the failure is very unlikely. This erratum has not been observed on the MPC8610, but the possibility still exists.

Workaround:	Customers may be able to find Core:MPX multiplier ratios that do not result in the processor hanging the system when this erratum is encountered; the address and address transfer attributes may have a modified output valid timing but may be sufficient to meet the receiving device's input setup times. If this erratum is encountered, debugging software at another Core:MPX ratio is possible. The store type operations will not complete until resuming from softstop state or single-stepping beyond the store type operation. Enabling address bus parking with the processor will reduce the chance of incurring this erratum.
Fix plan:	No plans to fix

JTAG 3: Boundary scan test on SerDes transmitter pins needs special requirement incompliant to IEEE 1149.1 specification

- Description:** The IEEE 1149.1 EXTEST or CLAMP specification requires to drive all output/bidirectional pins to a logical 1 at the same time. However, if this requirement is followed when executing the 1149.1 EXTEST or CLAMP command to drive SerDes transmitter pins, incorrect data will be present on SerDes pins during the boundary scan test.
- Impact:** A user will have to scan in all zeroes to the boundary cells associated with non-SerDes pins when testing the SerDes pins. There is no requirement in regards to testing all other pins.
- Workaround:** When executing the 1149.1 EXTEST or CLAMP command to drive SerDes transmitter pins, the user must scan in logic 0 to the boundary cells associated with non-SerDes pins, or configure all non-SerDes pins as inputs.
- Fix plan:** No plans to fix

eLBC1: Multi-bank DRAM and SDRAM will not work without any external logic

Description:	When the UPM is connected to multi-bank DRAM and SDRAM, the memories require that the bank address should be driven during both RAS and CAS cycles. However, due to the internal implementation, that does not happen.
Impact:	Multi-bank memories (DRAM/SDRAM) will not work as expected with the UPM.
Workaround:	An external intelligent logic can be used on the board as a workaround.
Fix plan:	No plans to fix

eLBC 2: LTEATR and LTEGR may show incorrect values under certain scenarios

Description:	The eLBC IP acks any transaction request when FCM special operation is in progress. In such a scenario when any one of the errors/events occur (such as Bus Monitor Timeout, Write Protect, Parity error, Atomic error, FCM command completion, or UPM command completion except for the CS error), the registers LTEGR and LTEATR capture the address and attributes of the most recently req-acked transaction instead of the FCM special operation that caused error. Hence indeterministic value may show up in those registers.
Impact:	LTEGR and LTEATR cannot be used for debugging in this scenario.
Workaround:	None
Fix plan:	No plans to fix

eLBC 3: UPM does not have indication of completion of a Run Pattern special operation

Description: A UPM or FCM special operation is initiated by writing to MxMR[OP] or FCM[OP] and then triggering the special operation either through the LSOR register or by performing a dummy access to the bank.

The UPM and FCM are expected to have different indications of when the special operation is completed. The FCM will see the LTESR[CC] bit set when such a special operation is completed. The UPM will see MxMR[MAD] increment when a write to or read from UPM array special operation completes. However, the UPM does not have any status indication of completion of the run pattern special operation.

The following two scenarios could be affected by this erratum:

1. A UPM Run Pattern special operation is initiated and a second UPM command is issued before the Run Pattern is completed.

If the above scenario occurs the programmed mode registers could be altered according to the second operation and cause the current/first operation to encounter errors due to mode changes in the middle of the operation. Note that if the second command issued is a Run Pattern operation and it does not change the mode registers, the first operation should not encounter errors.

2. A write to LSOR initiates a UPM Run Pattern special operation and then LSOR is written too again, to initiate a second special operation that requires the mode registers to change while the first Run Pattern operation is in progress.

If the second special operation issued does not change the programming mode of the first Run Pattern operation because the operation is either exactly the same as the first or it requires programming of an independent set of registers then the Run Pattern operation should not encounter errors.

The behavior of the eLBC is unpredictable if the Run Pattern special operation mode is altered between initiation of the operation and the relevant memory controller completing the operation.

Impact: Because of this erratum, when a UPM run pattern special operation is to be followed by any other UPM command for which the mode registers need to change, the Run Pattern operation may not be handled properly. Software does not have any means to confirm when the current run pattern special operation has completed so that register programming for the next operation can be done safely.

Workaround: None

Fix plan: No plans to fix

MCM 1: Unmapped tlbie EA causes local access window error

Description: A **tlbie** transaction uses an effective address rather than a real address, and should not participate in system address mapping in the MCM because **tlbie** is an address only transaction. However, if the effective address in a **tlbie** transaction does not match any local access window (LAW) in the MCM, it will trigger a local access error by setting EDR[LAE] = 1 and an interrupt when EER[LAEE] = 1.

Impact: A **tlbie** transaction may cause a local access error.

Workaround: Option 1: Enable local access error interrupts by EER[LAEE] = 1. When the MCM reports detected errors as interrupts, clear EDR[LAE] bit by writing a b'1 to EDR[LAE] if the following conditions are all true:

1. EDR[LAE] is set.
2. EATR[SRC_ID] = 10000 (core instruction)
3. EATR[TTYPE] is 1010.

Option 2: Set HID1[ABE] = 0. This will prevent the broadcasting of **tlbie**, as well as other cache operations (dcbf, dcbs, dcbsi, icbsi) and tlbsync.

Fix plan: No plans to fix

PEX 2: Completion Timeout error disable corrupts CRS threshold error data

Description:	Several attributes of enabled error conditions are written to the PEX Error Capture Status register (offset 0xE20) when an error condition is detected. If PEX_ERR_DISR[PCTD]=1 (disable detection of Completion Timeout threshold errors), then the global source ID attribute (PEX_ERR_CAP_R2[19:24]) for CRS Threshold errors will be incorrect.
Impact:	An incorrect global source ID is captured in PEX Error Capture Status register for CRS Threshold errors if Completion Timeout errors are disabled.
Workaround:	Enable Completion Timeout and CRS threshold error detection by keeping the default setting of PEX_ERR_DISR[PCTD]=0 and PEX_ERR_DISR[CRSTD] = 0.
Fix plan:	No plans to fix

PEX 3: No mechanism for recovery from hang after access to down link

Description:	When its link goes down, the PCI Express controller clears all outstanding transactions with an error indicator and sends a link down exception to the interrupt controller if PEX_PME_MES_DISR[LDDD] = 0. If, however, any transactions are sent to the controller after the link down event, they will be accepted by the controller and wait for the link to come back up before starting any timeout counters (e.g. completion timeout). There is no mechanism to cancel the new transactions short of a device HRESET.
Impact:	New transactions sent to a PCI Express link which is down will not complete or invoke a recoverable time out until the link recovers. The outstanding transactions may cause a core or other master (e.g. DMA) hang or a core watchdog timeout.
Workaround:	The problem can be mitigated by ensuring that link down exceptions are enabled (PEX_PME_MES_DISR[LDDD] = 0), and cause access to the PCI Express interface to be disabled for the duration of the link down. Note that PCI Express controller access can be via normal reads and writes (LAW/ATMU target) or by reads or writes to CONFIG_DATA in the PCI Express controller memory-mapped register space. Both types of access must be prevented. This does not completely eliminate the problem, because there could be accesses to the PCI Express interface between the time the link goes down and the time the interrupt handler disables access to the interface. In this instance device HRESET is required.
Fix plan:	No plans to fix

PEX 4: Reads to PCI Express CCSR or local config space temporarily return all Fs

Description:	<p>When its link goes down the PCI Express controller clears all outstanding transactions and, if PEX_PME_MES_DISR[LDDD]=0 and PEX_PME_MES_IER[LDDIE]=1, sends a link down exception to the interrupt controller. Read transactions are cleared with an error indicator (transaction error to source for memory reads, return data all Fs for config reads). Write transactions are silently dropped.</p> <p>The canceling of config read or write transactions should not apply to accesses to configuration, control and status registers in memory-mapped space or local PCI Express config space. Writes to memory-mapped or local PCI Express config registers are handled normally. However, due to this erratum, reads return all Fs for the duration of the link down cleanup.</p> <p>If the controller is configured as an endpoint and receives a hot reset request, it also brings the link down and follows the same cleanup procedures as in an externally detected link down. Note that reads to PCI Express memory-mapped registers or config registers will return all Fs for the duration of the hot reset event, as well.</p>
Impact:	<p>Reads to configuration, control and status registers in the memory-mapped or config space of PCI Express return all Fs during link down cleanup or hot reset event.</p> <p>During this time, writes are handled normally, though the results of the write are not verifiable.</p> <p>The duration of the link down cleanup varies depending on the number and type of pending transactions. Cleanup for pending outbound transactions takes just a few cycles, regardless of the source. Pending inbound transactions wait for all responses from targets (data response for reads, or successful arbitration to the target queue for writes) before completing cleanup.</p> <p>Once all pending transactions have been cleared, new CCSR accesses and local config return to normal operation.</p> <p>Note that because of PEX 3, any new accesses to PCI Express, including config reads to off-chip registers, will wait until the link resumes normal operation to complete. The config access state machine is serialized, so a config read to an off-chip register will prevent access to local CCSR or local config operations while the link remains down.</p>
Workaround:	<p>If the configuration, control or status register cannot return all Fs as a legal value, but does, keep polling the register value until it is not all Fs. Note that PEX_PME_MES_DR, the detect register containing the link down detect bit, cannot return all Fs in normal operation.</p> <p>If the configuration, control or status register can return all Fs as a legal value, and does, read another register which is known not to contain all Fs (e.g. PEX_IP_BLK_REV1) to confirm that the link is not in hot reset or link down cleanup, then reread the original register.</p>
Fix plan:	No plans to fix

PCI 1: Assertion of **STOP** by a target device on the last beat of a PCI memory write transaction can cause a hang

Description:	<p>As a master, the PCI IP block can combine a memory write to the last PCI double word (4 bytes) of a cacheline with a 4 byte memory write to the first PCI double word of the subsequent cacheline.</p> <p>This only occurs if the second memory write arrives to the PCI IP block before the deassertion of FRAME for the first write transaction. If the writes are combined, the PCI IP block masters a single memory-write transaction on the PCI bus. If for this transaction, the PCI target asserts STOP during the last data beat of the transaction (FRAME is deasserted, but TRDY and IRDY are asserted), the transaction completes correctly. A subsequent write transaction other than an 8-byte write transaction causes a hang on the bus. Two different hang conditions can occur:</p> <ul style="list-style-type: none">• If the target disconnects with data on the first beat of this last write transaction, the PCI IP block deasserts IRDY on the same cycle as it deasserts FRAME (PCI protocol violation), and no more transactions will be mastered by the PCI IP block.• If the target does not disconnect with data on the first beat of this last write transaction, IRDY will be deasserted after the first beat is transferred and will not be asserted anymore after that, causing a hang.
Impact:	<p>This affects 32-bit PCI target devices that blindly assert STOP on memory-write transactions, without detecting that the data beat being transferred is the last data beat of the transaction. It can cause a hang.</p> <p>If the PCI transaction is a one data beat transaction and the target asserts STOP during the transfer of that beat, there is no impact.</p>
Workaround:	<p>A PCI target device could avoid asserting STOP# during the last beat of a PCI memory write transaction that is greater than one data beat and crosses a cacheline boundary. It could assert STOP# during the last data beat of the cacheline or not assert STOP# at all. A software workaround for this problem is to set the PCI Latency Timer Register (offset 0x0D) to zero. A value of zero is the reset value for this register, so if this register is kept unmodified after reset, it will prevent the PCI IP block from ever combining writes.</p> <p>A debug bit, bit 10 of the PCI Bus Function Register (address 0x44) has been identified as another workaround. This bit, MDS (Master disable streaming), when set, will disable the combining of crossing cacheline boundary requests into one burst transaction,. Therefore, it can prevent the errata scenario from occurring. When this bit 10 is set, customer can program the PCI Latency Timer to achieve full cacheline burst even with one request in the PCI pipe.</p>
Fix plan:	No plans to fix

SPI 1: Selection of GPIO functionality on SPISEL signal causes MME in SPI

Description:	If SPI is being used in master mode and the <u>SPISEL</u> signal is programmed to operate with GPIO functionality (GPIOCR[UART0]=11 for SPI andGPIOCR[I2C2_SDA]=1 for GPIO), a multiple master error (MME) can occur if the pin is driven low due to the fact that the pin retains the <u>SPISEL</u> functionality in addition to the programmed GPIO functionality.
Impact:	While using SPI in master mode, GPIO2[12] cannot be used to select slave devices.
Workaround:	GPIOCR[I2C2_SDA] should be set to 1b'0 when GPIOCR[UART0] is set to 2b'11 and SPI is used in master mode (SPMODE[M/S]=1). When in master mode, a separate GPIO should be used to act as a slave select. As described in the reference manual, if the SPI is used in single-master mode, the master's <u>SPISEL</u> input should be forced inactive by an external pull up.
Fix plan:	No plans to fix

PMON 1: Some local bus events are not counted correctly in the performance monitor

Description: The "Number of accesses hitting banks (chip-selects) 1-8" events for the eLBC are not counted correctly.

Impact: These local bus events can not be used in the performance monitor.

Workaround: None

Fix plan: No plans to fix

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Document Number: MPC8610CE

Rev. 0
01/2010

